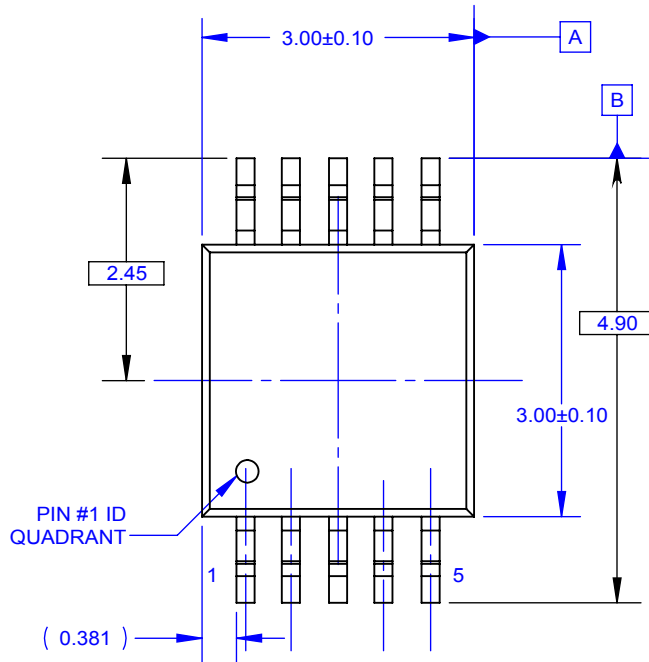


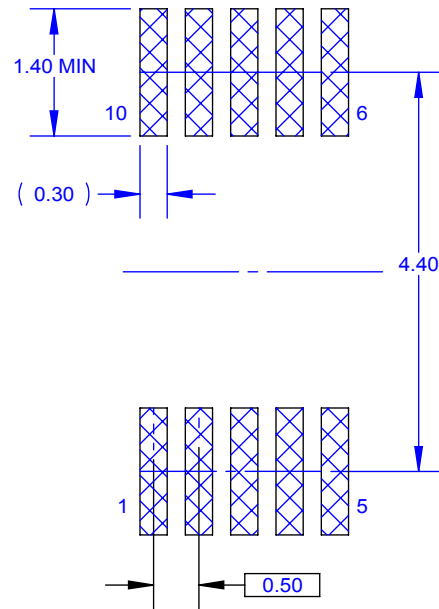
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REVISIONS

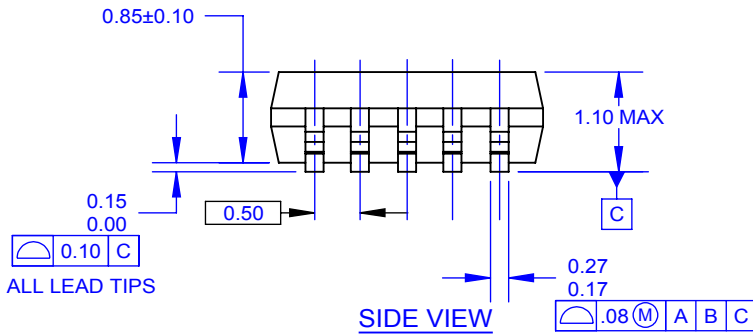
NBR	DESCRIPTION	DATE	BY/APP'D
B	REDREW FORMER NSC DWG	07JUN2006	H.ALLEN
2	* REMOVE SITE ADDRESS AND CHANGE REVISION TO NUMERICAL & CHANGED LAND PATTERN TO IPC. * CHANGE LEAD WIDTH FROM 0.27MM MAX TO 0.33MM MAX. * REMOVE DATE OF JEDEC REVISION	20AUG2009	KHLEE/FSSZ
3	* REVERT LEAD WIDTH TO 0.27MM MAX.	24SEP2009	KHLEE/FSSZ



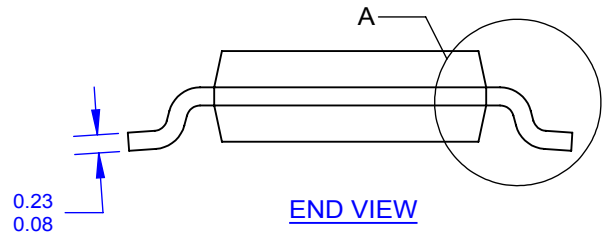
TOP VIEW



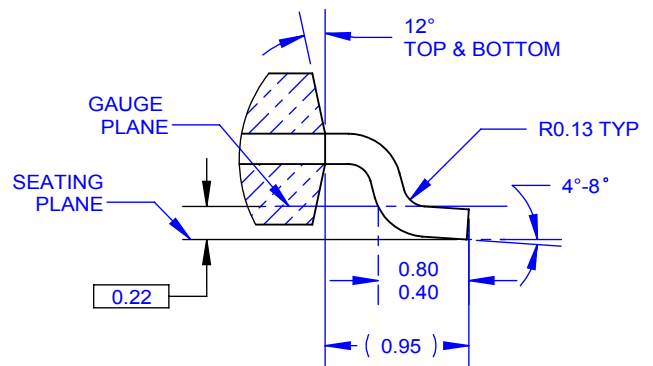
LAND PATTERN RECOMMENDATION



SIDE VIEW



END VIEW



DETAIL A
SCALE 20 : 1

NOTES: UNLESS OTHERWISE SPECIFIED

- A. THIS PACKAGE CONFORMS TO JEDEC MO-187 VARIATION BA.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES AS PER ASME Y14.5-1994.
- E. LAND PATTERN AS PER IPC7351#SOP50P490X110-10AN
- F. FILE NAME: MKT-MUA10AREV3

APPROVALS		DATE				
DRAWN: BOBOY MALDO		24SEP09				10LD, MSOP, JEDEC MO-187, 3.0MM WIDE
CHECKED: KH LEE						
APPROVED: BY HUANG						
APPROVED: HOWARD ALLEN						
PROJECTION			SCALE 1:1	SIZE N/A	DRAWING NUMBER MKT-MUA10A	REV 3
			FORMERLY: N/A		SHEET: 1 OF 1	